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Revision History

Rev. Code	Date	By	Description
A	2015-02-28	Javen	1 Revision A release
B	2015-06-12	Javen	1 OSC issue: Add R518,R515,R513,Q501,Y503,r516,r517 2 VDD_ARM_SOC_IN voltage: Change R706 to 215K, R707 to 147K, R708 to 1.5M Change R513,R517 to DCDC_3V3 3 DDR3 write leveling issue: exchang DDR3 DRAM_DATA3 and DRAM_DATA11 4 Add R519 for backup
C	2015-07-07	Javen	1 FCC update: Add C423,C415,R413,C414,C420,C417,C421,C416,C422,C418 2 VDD_HIGH_IN power consumption update: Change R513 from 10K to 1M Change R513,R517 to DCDC_3V3
	2015-07-14	Javen	3 Add R520 for OSC vih Change R510,C505 connection for OSC backup
A	2015-07-24	ChenWenhua	1 The changes based on MCIMX6UL-CM Version C 2 Replce discrete power with PF3000 Adding Li-cell charger circuit Reserve PF3000/3001 compatible design
B	2015-10-08	ChenWenhua	1 Change C705,C706,C801,R792 to DNP. 2 Add R810,R811,R812,R813
B	2015-11-03	ChenWenhua	1 Replace PF3000 with PF3001 Change R799,R800,R801,R802,R207,R208 to populated change L702,R763,R803 to DNP 2 Name the new project for PF3001 evaluation as KIT6UL-3001EVM
B1	2015-12-03	ChenWenhua	1 Change U44 to DNP
C	2016-1-7	ChenWenhua	1 Replace Q701 from FDMA908PZ to PMPB15XP, they are pin to pin
C1	2016-9-12	ChenWenhua	1 Align with MCIMX6UL-CM Version C5 DNP C414,R515,R513,Q501,Y503,R517 DNP R760,R812 Install R510,R518,R516,Y501, Install R759,R813 Change R520 to 499ohm,R514 from 1K to 0ohn 2 Change U101 CPU part number to MCIMX6G2CVM05AA New MFG_PN for U201: MT41K256M16TW-107:P
D	2017-6-12	ChenWenhua	1 Supply PF3001 VLDO34IN with a 3.3V DCDC

1. Unless Otherwise Specified:


- All resistors are in ohms, 10%, 1/8 Watt,0603
- All capacitors are in uF, 20%, 50V,0603
- All voltages are DC
- All polarized capacitors are aluminum electrolytic

2. Interrupted lines coded with the same letter or letter combinations are electrically connected.

3. Device type number is for reference only. The number varies with the manufacturer.

4. Special signal usage:
 _B Denotes - Active-Low Signal
 <> or [] Denotes - Vectored Signals

5. Interpret diagram in accordance with American National Standards Institute specifications, current revision, with the exception of logic block symbology.

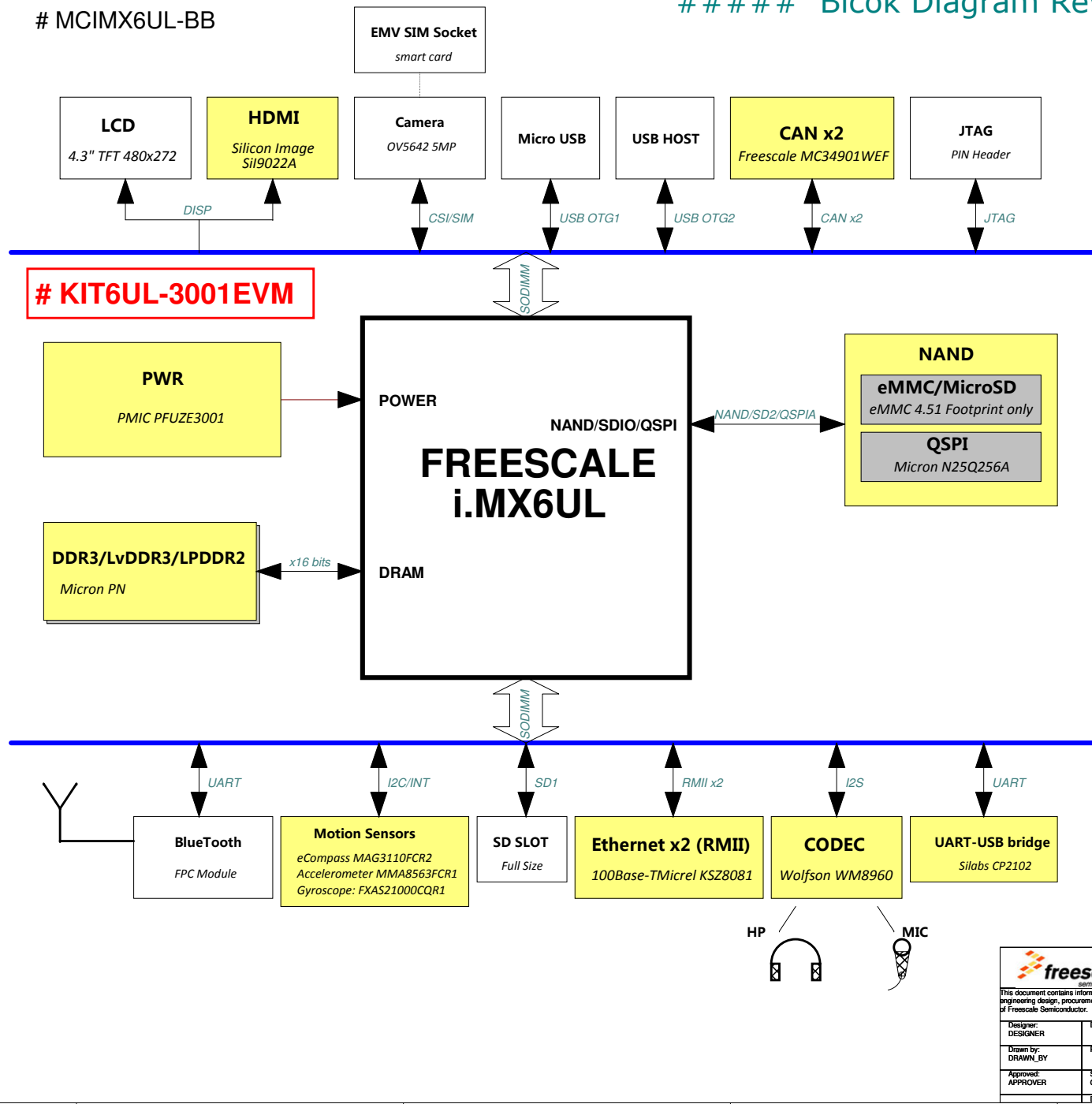
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Approved: APPROVER	Size C	Document Number SCH-29090 PDF: SPF-29090	Rev D
Date: Monday, June 12, 2017 Sheet 1 of 14			

i.MX6UL EVK Block Diagram

Bloc Diagram Rev 1.0

MCIMX6UL-BB

MPN: MCIMX6UL-BB Agile No: 28616
MPN: KIT6UL-3001EVM Agile No: 29090



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Drawn by: DRAWN_BY	Page Title: Block Diagram		
Approved: APPROVER	Size C	Document Number SCH-29090 PDF: SPF-29090	Rev D
Date: Monday, June 12, 2017		Sheet 2 of 14	

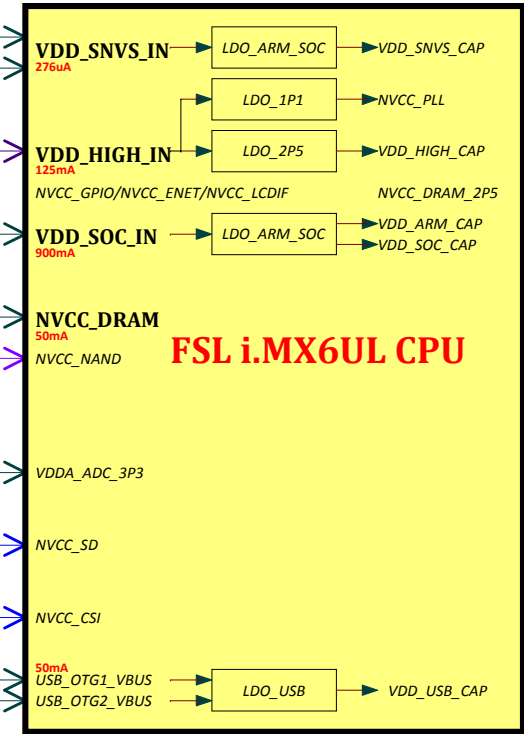
KIT6UL-3001EVM PWR TREE

WALL Adapter: 5V/3A

MCIMX6UL-BB

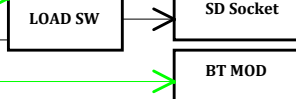
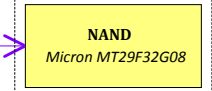
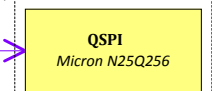
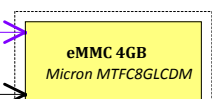
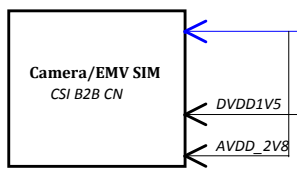
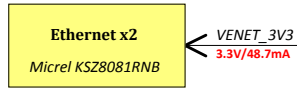
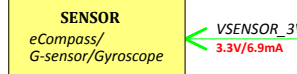
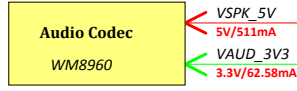
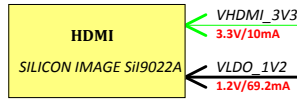
PFUZE3001	
VSNVS	3V / 1mA
V33	2.85V-3.3V / 350mA
SW1	0.7V-1.475V / 2.75A
SW2	(1.5V-1.85V)/(2.5V-3.3V) / 1.25A
SW3	0.9V-1.65V / 1.5A
VLDO3	1.8V-3.3V / 100mA
VLDO4	1.8V-3.3V / 350mA
VLDO1	1.8V-3.3V / 100mA
VLDO2	0.8V-1.55V / 250mA
VCC_SD	(1.8V-1.85V)/(2.85V-3.3V) / 100mA

LDO
 RICHTEK RT9169
 3.3V/100mA Iq = 4uA



LDO
 UNION UM1750S
 2.8V/300mA

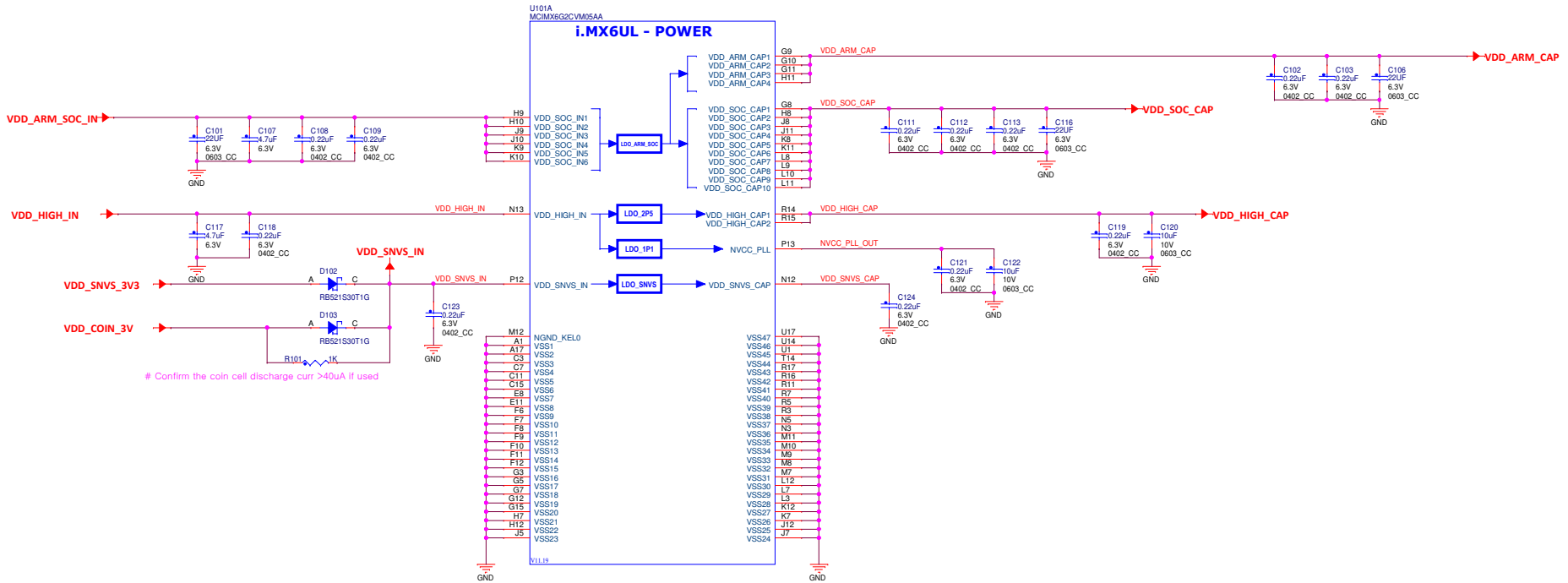
LOAD SW



KIT6UL-3001EVM

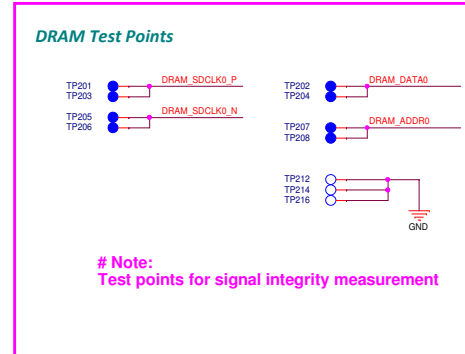
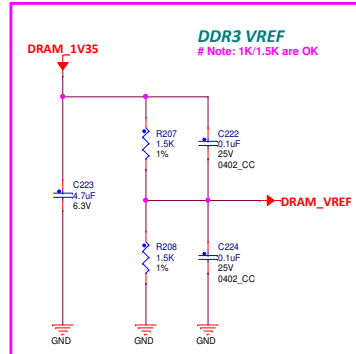
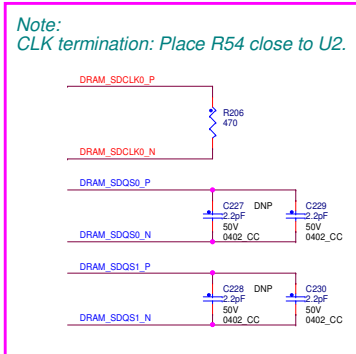
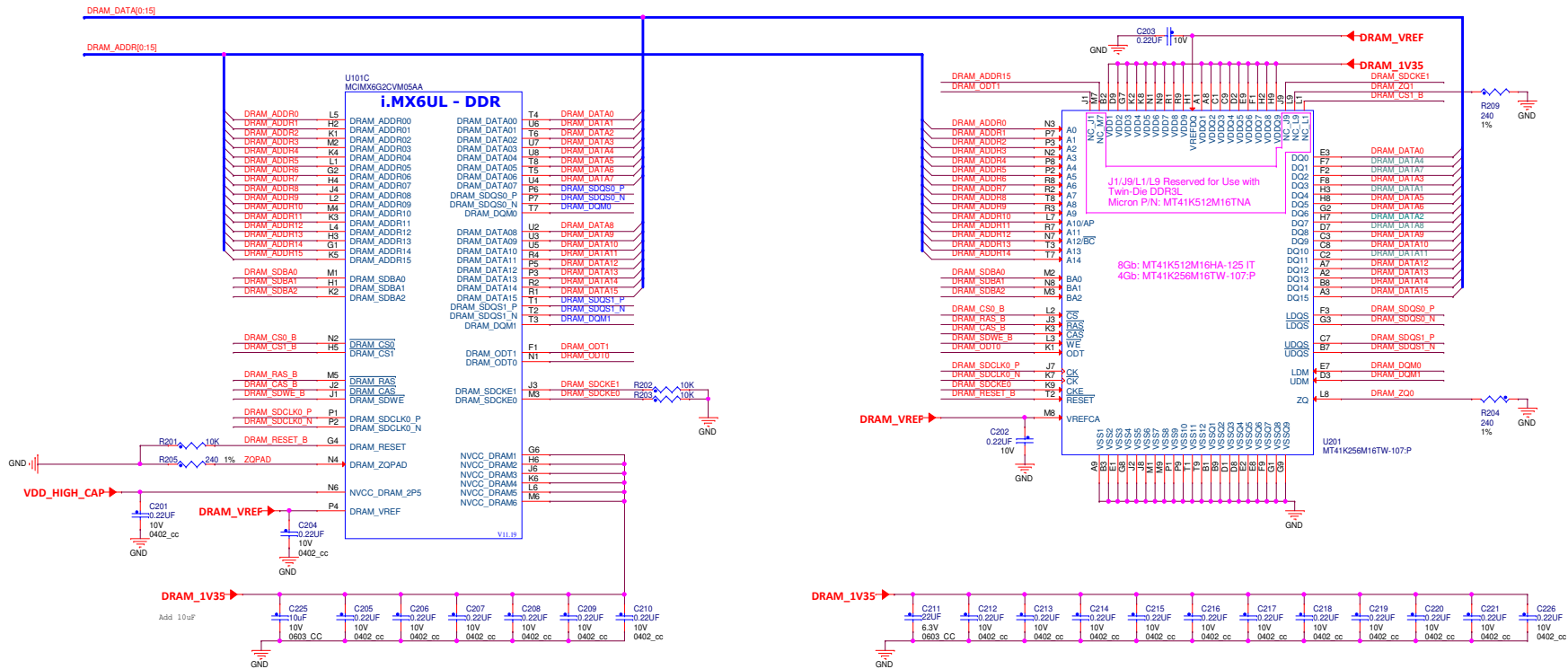
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DRAWN_BY		PWR TREE	
Approved:	Size C	Document Number	Rev D
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i.MX6UL PWR



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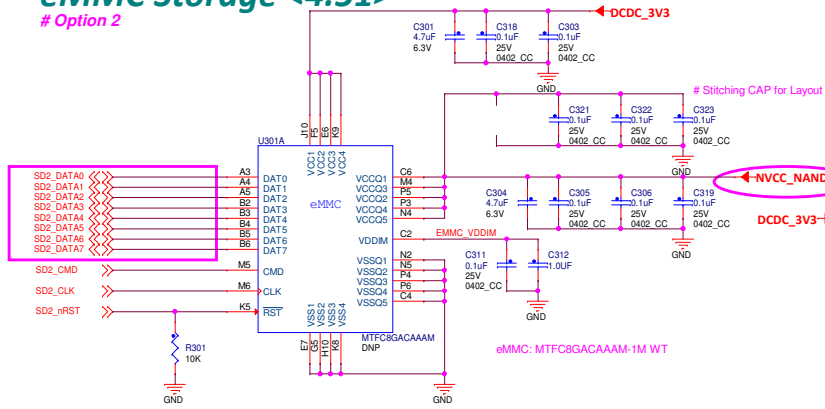
DDR3/LvDDR3



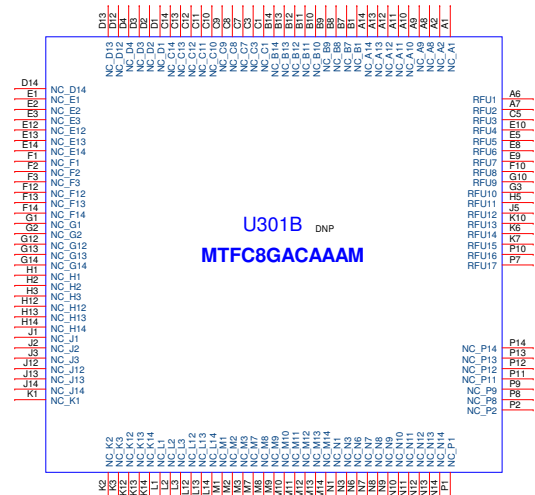
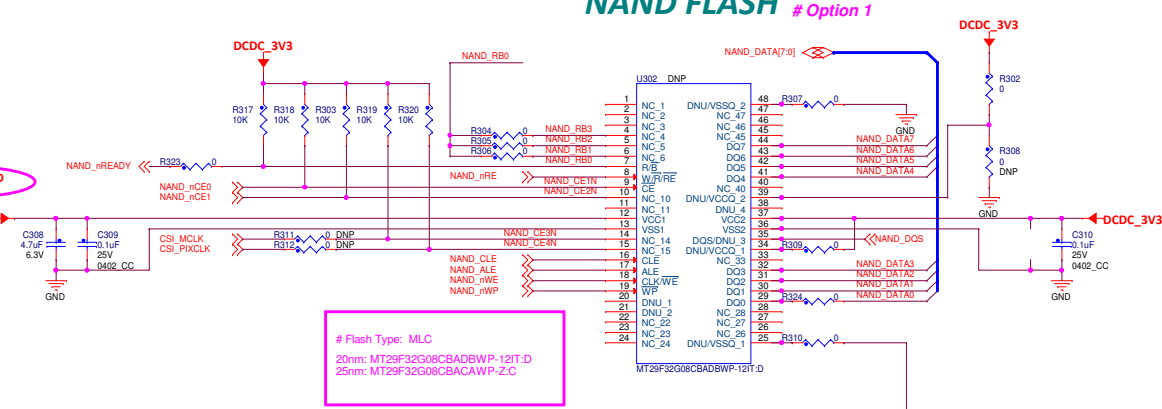
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		Sheet 5 of 14	

eMMC Storage <4.51>

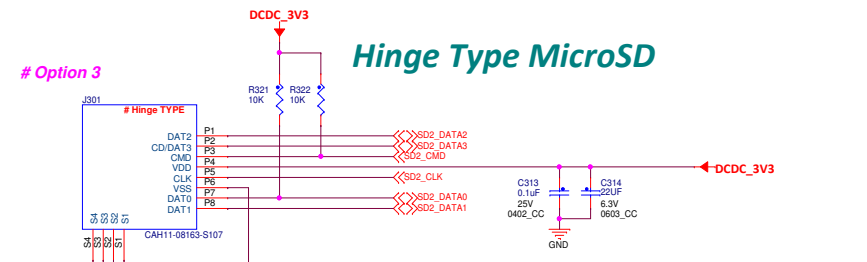
Option 2



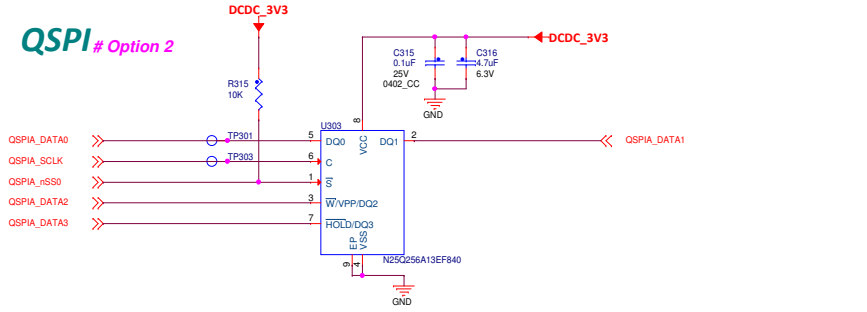
NAND FLASH # Option 1



Hinge Type MicroSD

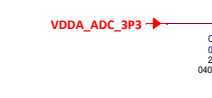
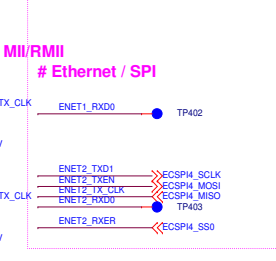
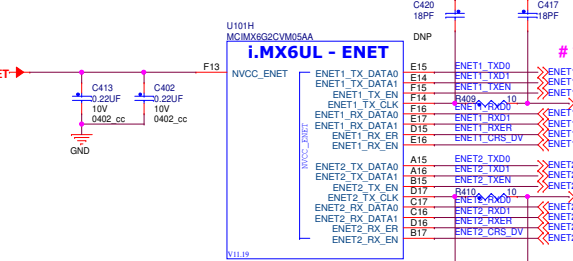
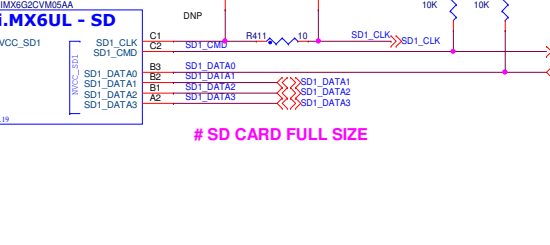
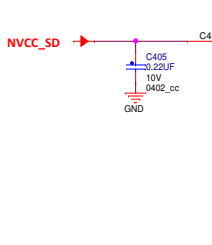
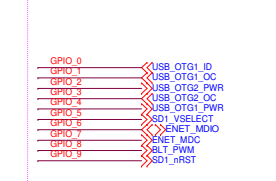
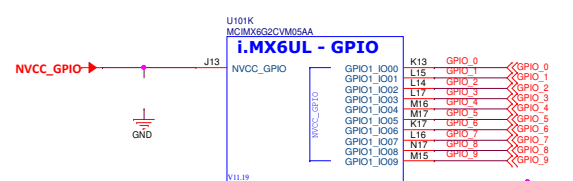
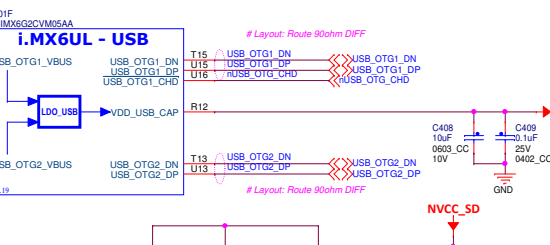
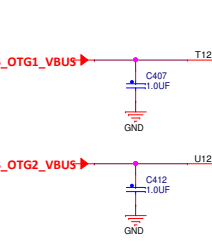
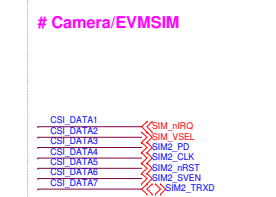
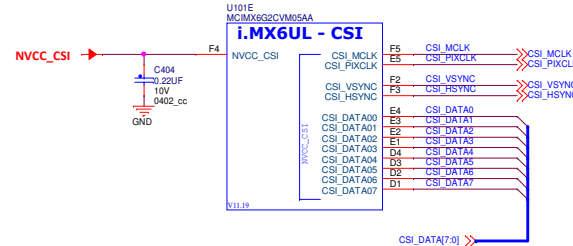
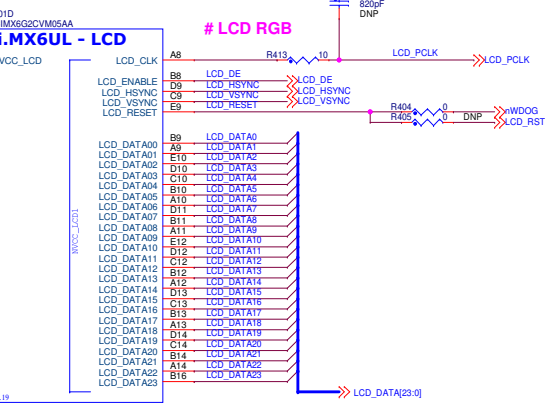
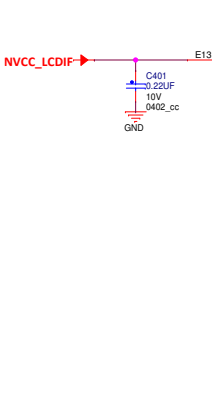
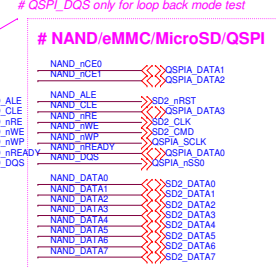
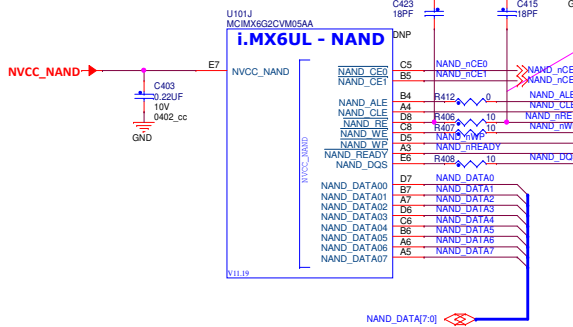


QSPI # Option 2



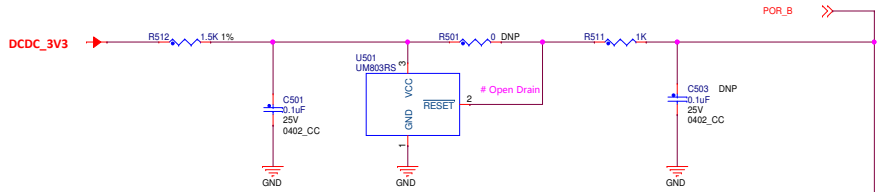
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Approved:	APPROVER	Size:	C
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Date:	Monday, June 12, 2017	Sheet:	6 of 14

MX6UL PERI

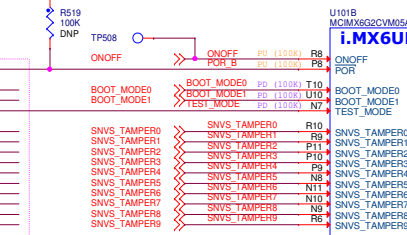


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Drawn by: DRAWN_BY	Page Title: CPU PERI x1	Size C	Document Number SCH-29090 PDF: SPF-29090
Approved: APPROVER	Date: Monday, June 12, 2017	Rev D	Sheet 7 of 14

i.MX6UL RESET



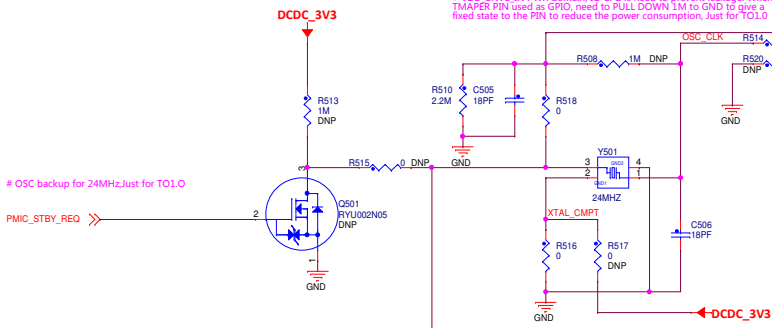
VDD_SNV5_IN



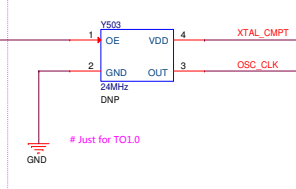
JTAG Debug



VDD_SNV5_IN in PWR domain, IO_CFG is need to prevent leakage. When TAMPER PIN used as GPIO, need to PULL DOWN 1M to GND to give a fixed state to the PIN to reduce the power consumption, Just for TOL0

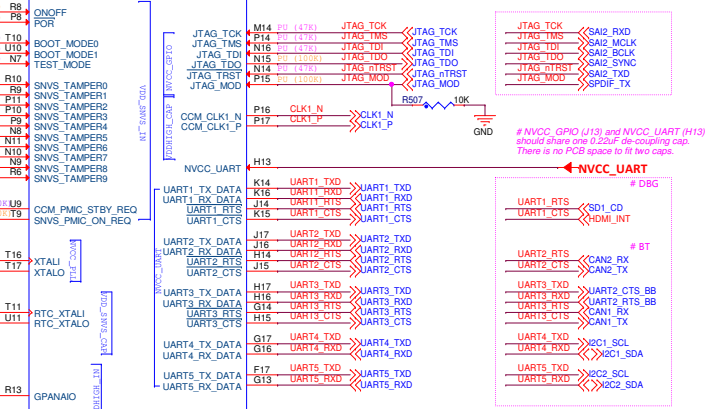


OSC backup for 24MHz, Just for TOL0



Just for TOL0

i.MX6UL - CONTROL



JTAG_TCK SA12_RXD
JTAG_TMS SA12_MCLK
JTAG_TDI SA12_BCLK
JTAG_TDO SA12_TXD
JTAG_rTRST SA12_TXD
JTAG_MOD SPOIF_TX

NVCC_GPIO (J13) and NVCC_UART (H13) should share one 0.22uF decoupling cap. There is no PCB space to fit two caps.

DBG
UART1_RTS SD1_CD
UART1_CTS HDN_INT

BT
UART2_RTS CAN2_RX
UART2_CTS CAN2_TX

UART3_TXD UART2_CTS_BB
UART3_RXD CAN1_RX
UART3_RTS CAN1_TX

UART4_TXD X2C1_SCL
UART4_RXD X2C1_SDA
UART5_TXD X2C2_SCL
UART5_RXD X2C2_SDA

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FUSE MAP

<Default: QSPI BOOT>

TYPE	BOOT_CFG1[7]	BOOT_CFG1[6]	BOOT_CFG1[5]	BOOT_CFG1[4]	BOOT_CFG1[3]	BOOT_CFG1[2]	BOOT_CFG1[1]	BOOT_CFG1[0]
QSPI	0	0	0	1	Reserved	Reserved	Reserved	Reserved
WEIM	0	0	0	0	Memory Type: 0 - NOR Flash 1 - OneNAND	Reserved	Reserved	Reserved
Serial-ROM	0	0	1	1	Reserved	Reserved	Reserved	Reserved
SD/eSD	0	1	0	Fast Boot: 0 - Regular 1 - Fast Boot	SD/SDXC Speed 00 - Normal/SDR12 01 - High/SDR25 10 - SDR50 11 - SDR104	SD Power Cycle Enable 0 - No power cycle 1 - Enabled via LSDHC_RST pad (LSDHC3 & 4 only)	SD Lookback Clock Source Setting: SDR50 and SDR104 only 1 - through SD pad 1' - direct	
MMC/eMMC	0	1	1	Fast Boot: 0 - Regular 1 - Fast Boot	SD/MMC Speed 0 - High 1 - Normal	Fast Boot Acknowledge Disable: 0 - Boot Ack Enabled 1 - Boot Ack Disabled	SD Power Cycle Enable 0 - No power cycle 1 - Enabled via LSDHC_RST pad (LSDHC3 & 4 only)	SD Lookback Clock Source Setting: SDR50 and SDR104 only 1' - through SD pad 1' - direct
NAND	1	BT_TOGGLEMODE	Fuses in block: 00 - 128 01 - 64 10 - 32 11 - 256		Normal Number of Devices: 00 - 1 01 - 2 10 - 4 11 - Reserved	NAND Row Address, Bytes: 00 - 3 01 - 2 10 - 4 11 - 5		

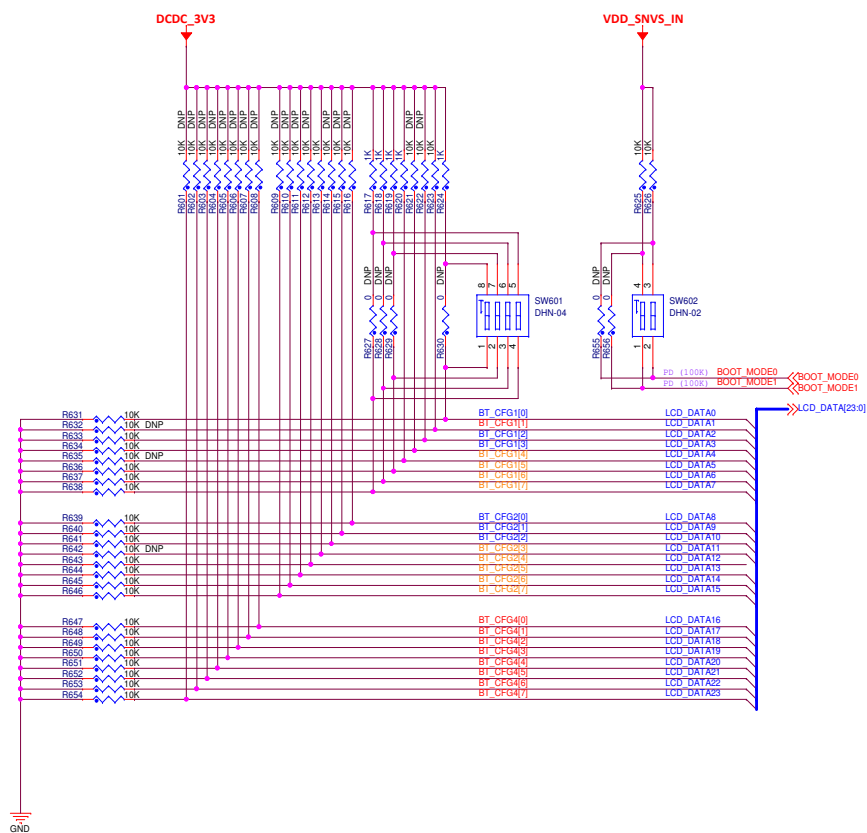
NAND MT29F32G08CBACA

1 page = (4k + 224 bytes)
 1 block = (4k + 224) bytes x 256 pages
 = 11024k + 508 bytes
 1 plane = (1024k + 56k) bytes x 2048 blocks
 = 17,280MB
 1 LUN = 17,280MB x 2 planes
 = 34,560MB

Boot Configuration

BMODE[1:0]	BOOT TYPE
00	Boot From Fuses
01	Serial Downloader
10	Internal Boot (Development)
11	Reserved

TYPE	BOOT_CFG2[7]	BOOT_CFG2[6]	BOOT_CFG2[5]	BOOT_CFG2[4]	BOOT_CFG2[3]	BOOT_CFG2[2]	BOOT_CFG2[1]	BOOT_CFG2[0]
QSPI	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
WEIM	Missing Scheme: 00 - A/D16 01 - A/H 10 - A/Hd 11 - Reserved		Overhead Page Size: 00 - 1KB 01 - 2KB 10 - 4KB 11 - Reserved		Reserved	Reserved	Reserved	Reserved
Serial-ROM	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved
SD/eSD	SD Calibration Step '00' - 1 TBD		Bus Width: 0 - 1-bit 1 - 4-bit		Port Select: 00 - eSDHC2 01 - eSDHC3 10 - Reserved 11 - Reserved	Boot Frequencies (ARM/DSP) 0 - 500 / 400 MHz 1 - 250 / 200 MHz	SD1 VOLTAGE SELECTION 0 - 1.8V 1 - 1.9V	Reserved
MMC/eMMC	Bus Width: 000 - 1-bit 001 - 4-bit 010 - 8-bit 011 - 8-bit 100 - 8-bit DDR (MMC 4.4) 110 - 8-bit DDR (MMC 4.4) Ebit - reserved		Port Select: 00 - eSDHC2 01 - eSDHC3 10 - Reserved 11 - Reserved		Boot Frequencies (ARM/DSP) 0 - 500 / 400 MHz 1 - 250 / 200 MHz	SD2 VOLTAGE SELECTION 0 - 1.8V 1 - 1.9V	Reserved	Reserved
NAND	Toggle Mode 15MHz Readable Delay, Read Latency: 000 - 6 GPMICLK cycles 001 - 1 GPMICLK cycles 010 - 2 GPMICLK cycles 011 - 3 GPMICLK cycles 100 - 4 GPMICLK cycles 101 - 5 GPMICLK cycles 110 - 6 GPMICLK cycles 111 - 7 GPMICLK cycles		BOOT_SEARCH_COUNT: 00 - 2 01 - 2 10 - 4 11 - 8		Boot Frequencies (ARM/DSP) 0 - 500 / 400 MHz 1 - 250 / 200 MHz	Boot Type: 0 - 22ns (eBA NAND) 1 - 22ns (eBA NAND)	Reserved	Reserved



TYPE	BOOT_CFG4[7]	BOOT_CFG4[6]	BOOT_CFG4[5]	BOOT_CFG4[4]	BOOT_CFG4[3]	BOOT_CFG4[2]	BOOT_CFG4[1]	BOOT_CFG4[0]
0x450	Infinite-Loop (Debug USE only) 0 - Disable 1 - Enable	EEPROM Recovery Enable 0 - Disabled 1 - Enabled	CS select (SPI only): 00 - CS#0 (default) 01 - CS#1 10 - CS#2 11 - CS#3	SPI Addressing: 0 - 2-bytes (16-bit) 1 - 3-bytes (24-bit)	Port Select: 000 - eCSP1 001 - eCSP2 010 - eCSP3 011 - eCSP4 100 - Reserved 101 - Reserved 110 - Reserved 111 - Reserved	Reserved	SEC_CONFIG[1]	Reserved
0x460	L2_HW_INVALIDATE_DISABLE	Reserved	FORCE_COLD_BOOT (Reflected in SBMR2)	BT_FUSE_SEL	DIR_BT_DIS	Reserved	SEC_CONFIG[1]	Reserved
0x460	Reserved (DDR3 config options)							
0x460	JTAG_SMODE[1:0]	WDG_ENABLE 0 - Disabled 1 - Enabled	SJC_DISABLE	Reserved	Reserved	Reserved	Reserved	Reserved
0x460	Reserved	Reserved	Reserved	TZASC_ENABLE	JTAG_HEO	KTE	Reserved	Reserved
0x470	DLL Override: 0 - DLL Slave Mode for SD/eMMC 1 - DLL Override Mode for SD/eMMC	Reserved	SD2 VOLTAGE SELECTION 0 - 3.3V 1 - 1.8V	Reserved	Disable SDRAM Manufacture mode 0 - Enable 1 - Disable	L1 I-Cache DISABLE	BT_MMU DISABLE	Override Pad Settings (using PAD_SETTINGS value)
0x470	Reserved for unexpected requirements	eMMC 4.4 - RESET TO PRE-IDLE STATE	Override HYS bit for SD/MMC pads	USDC_PAD_PULL_DOWN 0 - no action 1 - pull down	ENABLE_EMMC_22K_PULLUP 0 - 47k pullup 1 - 22k pullup	ADD_DS_SET_GRP1_16 0 - Set 1 - Don't set	USDC_IDMUX_SION_BIT_ENABLE 0 - Disable 1 - Enable	USDC IDMUX SRE Enable 0 - Disable 1 - Enable
0x470	USDC_CMD_OE_PRE_EN (SD/eMMC debug)	LPB_BOOT (Core / DDR3 Bus) '00' - LPB Disable '01' - 1 GPIO (def Pre) '10' - Div by 2 '11' - Div by 4	BT_LPB_POLARITY (GPIO polarity)	POWER_MNG_CFG (LDO's DCDC's) (Reserved - NOT USED)				
0x470	Override NAND Pad Settings (using PAD_SETTINGS value)	MMC_DLL_DLY[6:0] Delay target for SD/eMMC DLL. It is applied to slave mode target delay or override mode target delay depends on DLL Override fuse bit value.						

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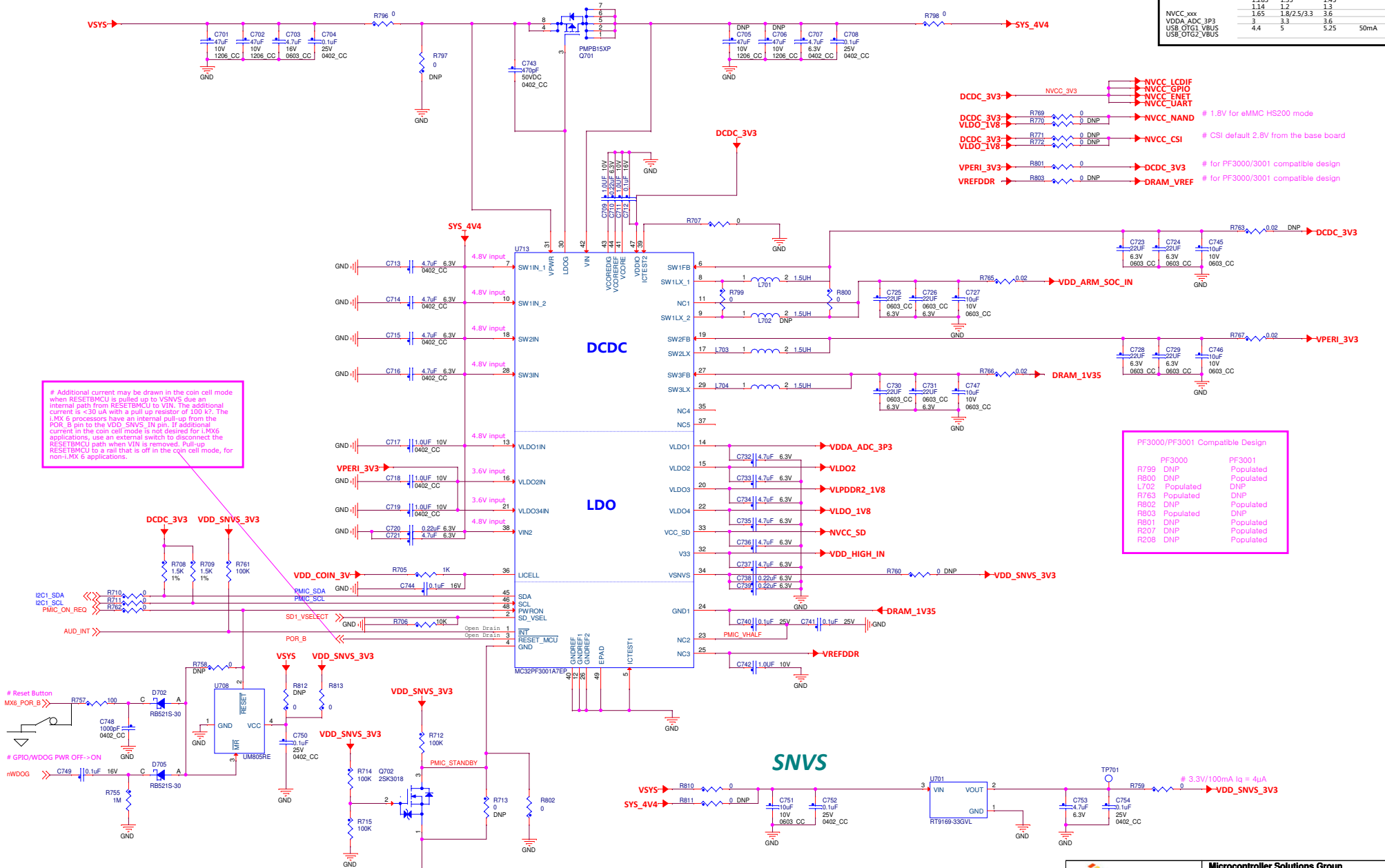
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ICAP Classification: FCP: _____ FUC: X PUB: _____

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Drawn by: DRAWN_BY	Page Title: BOOT CFG
Approved: APPROVER	Size C Document Number: SCM-29090 PDF: SPF-29090
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PFUZE3001 PMIC

i.MX6UL PWR				
Power Rail	MIN	TYP	MAX	CURR
VDD_SNV5_IN	2.4	3	3.6	276µA
VDD_HIGH_IN	2.8	3	3.6	125mA
VDD_ARM_IN	0.9	1.275	1.5	400mA
VDD_SOC_IN	0.9	1.275	1.5	500mA
NVCC_DRAM	1.425	1.5	1.575	50mA
	1.283	1.35	1.45	
	1.14	1.2	1.3	
	1.65	1.8/2.5/3.3	3.6	
NVCC_XXX	3	3.3	3.6	
VDDA_ADC_3P3	3	3.3	3.6	
USB_OTG1_VBUS	4.4	5	5.25	50mA
USB_OTG2_VBUS				



Additional current may be drawn in the coin cell mode when RESETMCU is pulled up to VSNS due an internal path from RESETMCU to VIN. The additional current is ~30 uA with a pull-up resistor of 100 kΩ. The i.MX6 processors have an internal pull-up from the POR_5 pin to the VDD_SNV5_IN pin. If additional current in the coin cell mode is not desired for i.MX6 applications, use an external switch to disconnect the RESETMCU path when VIN is removed. Pull-up RESETMCU to a rail that is off in the coin cell mode, for non-i.MX6 applications.

PF3000/PF3001 Compatible Design		
R799	DNP	Populated
R800	DNP	Populated
L702	Populated	DNP
R763	Populated	DNP
R802	DNP	Populated
R803	Populated	DNP
R801	DNP	Populated
R207	DNP	Populated
R208	DNP	Populated

When PMIC_STBY_REQ pad is driving high state in SUSPEN mode, the output voltage level is about 2.0V. This voltage is lower than the 3.0V VDD_SNV5_IN supply voltage.

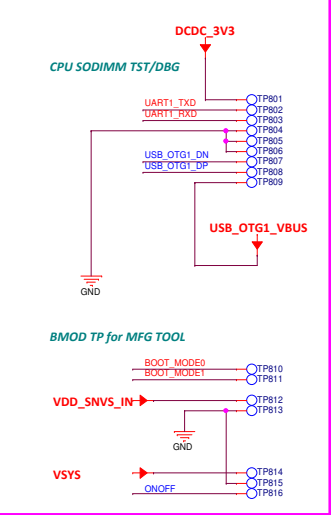
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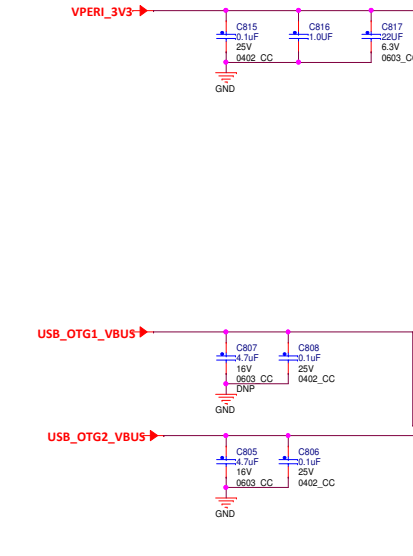
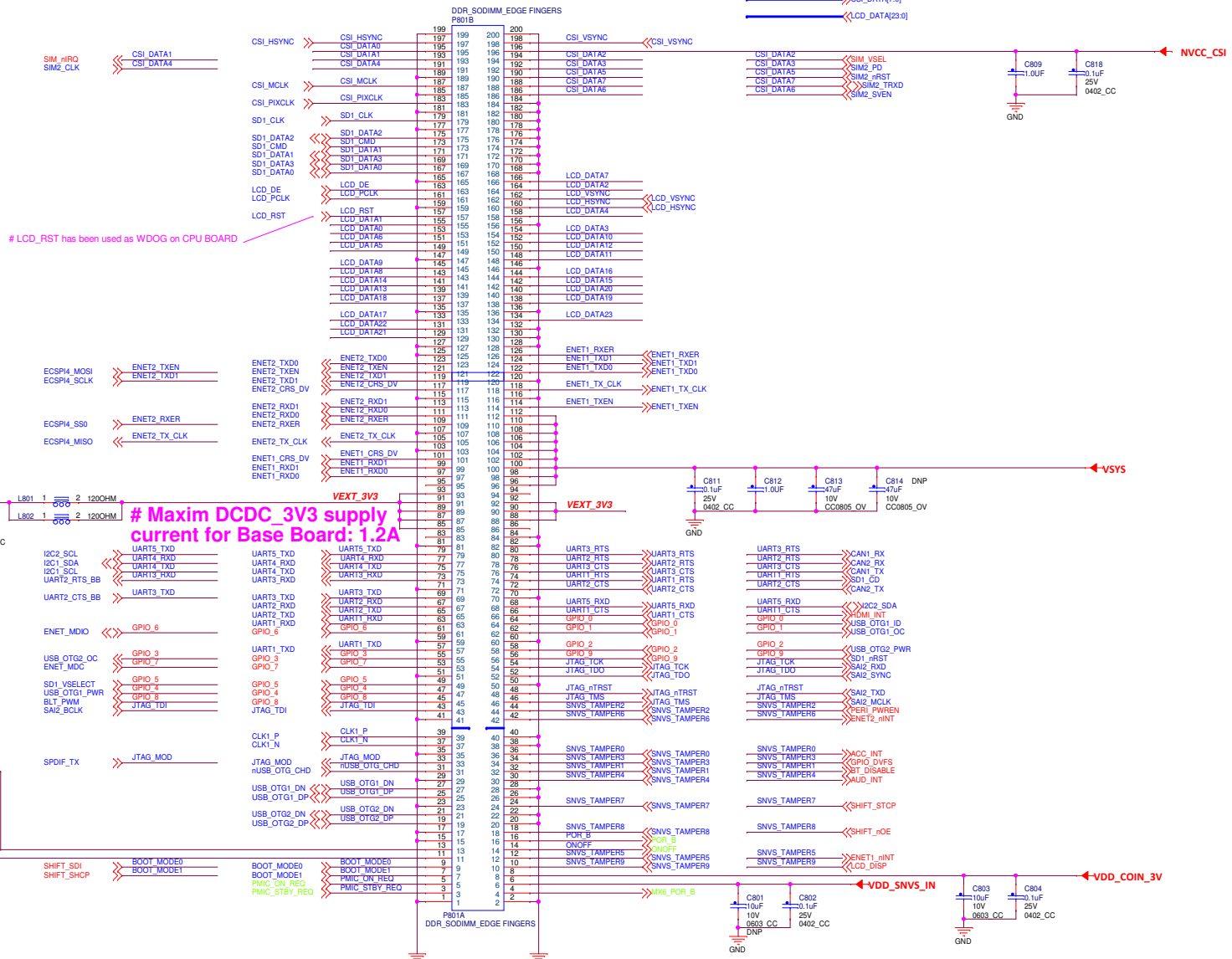
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TP for SODIMM MFG

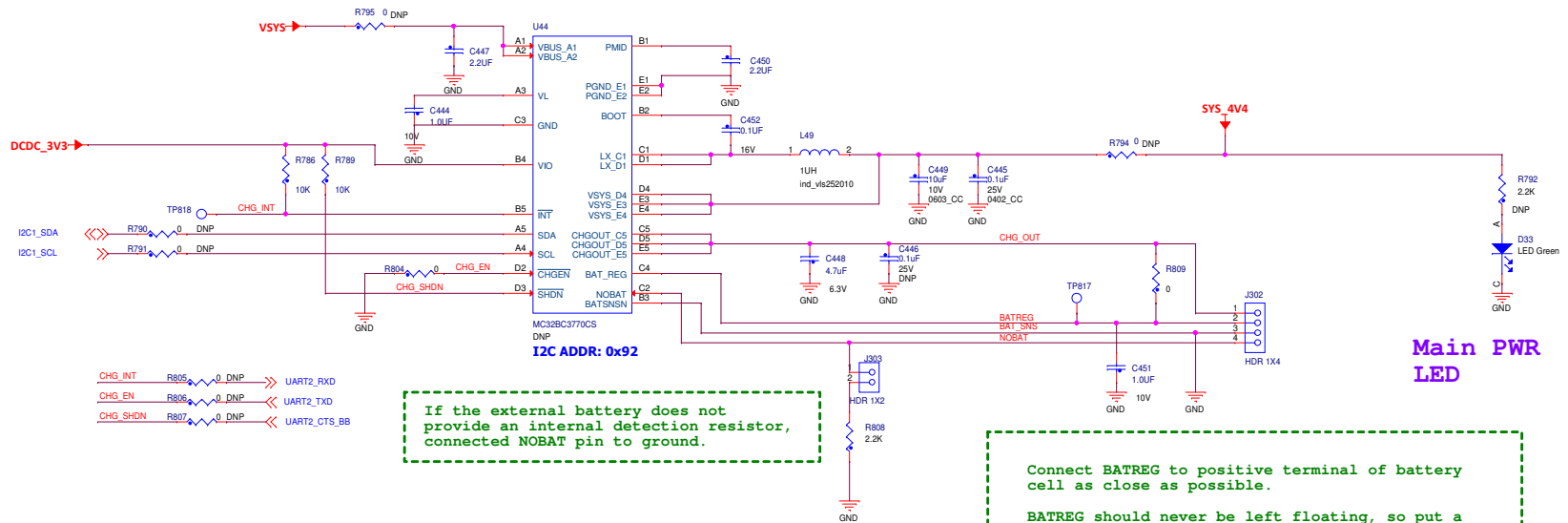


SODIMM 200



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Lithium Charger

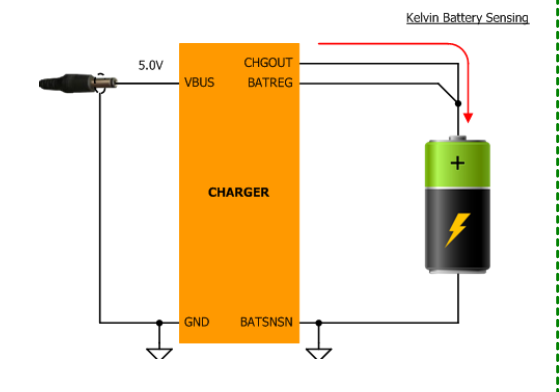


CHG_INT R805 0 DNP → UART2_RXD
 CHG_EN R806 0 DNP → UART2_TXD
 CHG_SHDN R807 0 DNP → UART2_CTS_BB

If the external battery does not provide an internal detection resistor, connected NOBAT pin to ground.

Connect BATREG to positive terminal of battery cell as close as possible.
 BATREG should never be left floating, so put a 0ohm between BATREG and CHGOUT in case BATREG isn't connected to battery external.

Note:
 For non-battery operated applications, when the input supply voltage exceeds 4.5 V, the front-end LDO can be activated by populating the external PMOS pass FET Q701 and connecting the VPWR pin to the main supply.
 In a battery operated application, BC3770 input is connected directly to the adapter. In this case, the PMOS pass FET Q701 should not be populated and VPWR pin should be grounded externally.



NOTE:

All pins using ~reset as harden :

PAD	Default State	Simulation Value
UART3_TX_DATA	Output Buffer(LOW) during reset --> Output keeper + Input enable after reset done	0 in real silicon
LCD_DATA00~LCD_DATA23	100K pull down + input enable during reset --> Output keeper + Input enable after reset done (this is boot option, we don't need change)	0 in real silicon

PAD	Default State	Signal Path	PAD Simulation Value
UART3_TX_DATA	Output Buffer(LOW) during reset --> Output keeper + Input enable after reset done	sjc.ipt_jta_active --> PAD	0 in real silicon
		(note : sjc.ipt_jta_active also connected to snvs_hp.sec_vio_in_1. This is security related, we don't plan to change it.)	ALT7


All pins using ~src.en_system_clk as harden :

PAD	Default State	Simulation Value
GPIO1_IO03	100K pull down + input enable during reset --> Output keeper + Input enable after reset done	0 in real silicon

PAD	Default State	Signal Path	PAD Simulation Value
GPIO1_IO03	100K pull down + input enable during reset --> Output keeper + Input enable after reset done	PAD --> ccmsrcmix. src_tester_ack	0 in real silicon
		This is the requirement of TE test	ALT7

All pins using snvs_hp.snvs_sec_vio_in_5_en as harden :

PAD	Default State	Simulation Value
CSI_PIXCLK	Output keeper + Input enable (snvs_sec_vio_in_5_en is 1'b0 in normal state, so harden is not triggerd in normal state). snvs_sec_vio_in_5_en is controlled by SNVS register. It can be disable or enable.	X (0 or 1 in real silicon)

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